	© Copyright 2005. If international and Pan	Osition Dec PC, Bannockb -American co	claration urn, Illinois. A pyright conver	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	ation c i encoi	of the substances mpasses all lowe	within th r level ma	e manufactur aterials for wi	er listed i hich the n	tem. Note nanufactur	: if the item is an as rer has engineering	ssembly with lowe responsibility.
1752-21.1					Form Type Distribute	 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater 					ials and Mfg Information				
Supplier	Information														
Company name* Company u				ny unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-16			
Contact Na	ame	Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized	Representative*	Title - Representative				Phone - Representative*				Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item 2SC5706						Effective Date Version Manufacturing Size 2024-05-16 CNG		uring Site	Weight* 322.17		UOM	Unit Type		
												mg	Each		
Aanufac	turing Proccess Informat	ion		·			•								
,	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-02		J-STD-020 MSI	L Rating	Peak Process B		Body Temperature Max		Гіте at Peak	Tempera	ure Nur	nber of Reflow Cyc	cles
contains Bi			CU Alloy NA				0 C 30				seconds 3				
Comments															
or more i	nformation regarding material	composition]	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.33	mg	Supplier	Silicon (Si)	7440-21-3		0.33	mg
Die Attach Solder	0.15	mg	Supplier	Silver (Ag)	7440-22-4		0.0038	mg
			А	Lead (Pb)	7439-92-1	7a	0.1388	mg
			Supplier	Tin (Sn)	7440-31-5		0.0075	mg
lead Frame	191.37	mg	Supplier	Silver (Ag)	7440-22-4		0.3827	mg
			Supplier	Tin (Sn)	7440-31-5		0.2679	mg
			Supplier	Copper (Cu)	7440-50-8		190.7193	mg
Mold Compound-Black	123.38	mg		Brominated epoxy resin	proprietary data		1.7273	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.5521	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1104	mg
			Supplier	Carbon Black (C)	1333-86-4		1.2338	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		92.535	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		20.9746	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2468	mg
lating	6.31	mg	В	Bismuth (Bi)	7440-69-9		0.0379	mg
			Supplier	Tin (Sn)	7440-31-5		6.2721	mg
Wire Bond - Au	0.63	mg	Supplier	Gold (Au)	7440-57-5		0.63	mg